

FAST CMOS 18-BIT READ/WRITE BUFFER

IDT74FCT162701T/AT

FEATURES:

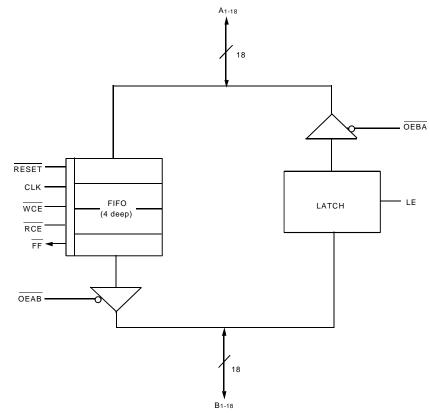
- 0.5 MICRON CMOS Technology
- Typical tsκ(o) (Output Skew) < 250ps
- Low input and output leakage ≤1µA (max.)
- ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
- Balanced Output Drivers (±24mA)
- · Reduced system switching noise
- Typical VolP (Output Ground Bounce) < 0.6V at Vcc = 5V, TA = 25°C
- · Ideal for new generation x86 write-back cache solutions
- Suitable for modular x86 architectures
- · Four deep write FIFO
- · Latch in read path
- Synchronous FIFO reset
- Available in SSOP and TSSOP packages

DESCRIPTION:

The FCT162701T is an 18-bit Read/Write buffer with a four deep FIFO and a read-back latch. It can be used as a read/write buffer between a CPU and memory or to interface a high-speed bus and a slow peripheral. The A-to-B (write) path has a four deep FIFO for pipelined operations. The FIFO can be reset and a FIFO full condition is indicated by the full flag (\overline{FF}). The B-to-A (read) path has a latch. A high on LE, allows data to flow transparently from B-to-A. A low on LE allows the data to be latched on the falling edge of LE.

The FCT162701T has a balanced output drive with series termination. This provides low ground bounce, minimal undershoot and controlled output edge rates.

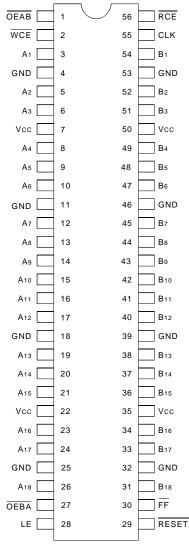
FUNCTIONAL BLOCK DIAGRAM



The IDT logo is a registered trademark of Integrated Device Technology, Inc.

JANUARY 2002

PIN CONFIGURATION



SSOP/ TSSOP TOP VIEW

PIN DESCRIPTION

Pin Names	I/O	Description
A1-18	I/O	18 bit I/O port
B1-18	I/O	18 bit I/O port
CLK	Ι	Clock for write path FIFO. Clocks data into FIFO when \overline{WCE} is low, clocks data out of FIFO when \overline{RCE} is low. When FIFO is full all further writes to the FIFO are inhibited. When FIFO is empty all reads from the FIFO are inhibited. CLK also resets the FIFO when \overline{RESET} is low.
WCE	I	Enable pin for FIFO input clock
RCE	I	Enable pin for FIFO output clock
FF	0	Write path FIFO full flag. Goes low when FIFO is full.
RESET	Ι	Synchronous FIFO reset - when low CLK resets the FIFO. The FIFO pointers are initialized to the "empty" condition and FIFO output is forced high (all ones). The FIFO full flag (FF) will be high immediately after reset.
OEAB	Ī	Output Enable pin for B port
ŌĒBĀ	Ī	Output Enable pin for A port
LE	I	Read path latch enable pin. When high, data flows transparently from B port to A port, B data is latched on the falling edge of LE.

INDUSTRIAL TEMPERATURE RANGE

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Description	Max	Unit
VTERM ⁽²⁾ Terminal Voltage with Respect to		–0.5 to 7	٧
VTERM ⁽³⁾	Terminal Voltage with Respect to GND	-0.5 to Vcc+0.5	٧
Tstg	Storage Temperature	-65 to +150	°C
Ιουτ	DC Output Current	-60 to +120	mA

NOTES:

 Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

2. All device terminals except FCT162XXX Output and I/O terminals.

3. Output and I/O terminals for FCT162XXX.

CAPACITANCE (TA = +25°C, f = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Тур.	Max.	Unit
CIN	Input Capacitance	VIN = 0V	3.5	6	pF
Соит	Output Capacitance	Vout = 0V	3.5	8	pF

NOTE:

1. This parameter is measured at characterization but not tested.

FUNCTIONAL DESCRIPTION

This device is useful as a read/write buffer for modular high end designs. It provides multi-level buffering in the write path and single deep buffering in the read path, and is suited to write back cache implementation. The read path provides a transparent latch.

The four deep FIFO uses one clock with two clock enable pins, WCE and RCE to clock data in and out. The FIFO has an external full flag which goes LOW when the FIFO is full. Internal read and write pointers keep track of the words stored in the FIFO. A write attempt to a full FIFO is ignored. An attempt to read from an empty FIFO will have no effect and the last read data remains at the output of the FIFO. The FIFO may be reset by the synchronous RESET

input. This resets the read and write pointers to the original "empty" condition and also sets all B outputs = 1. Simultaneous read and write attempts (clock data into FIFO as well as clock data out of FIFO) are possible except on FIFO empty and full boundaries. When the FIFO is empty, and a simultaneous read and write is attempted, the read is ignored while the write is executed. If the same is attempted when the FIFO is full, the write is ignored while the read is executed. Normal operation of the four deep FIFO in the write path is independent of the read path operation.

Power, ground and data pin positions on the FCT162701T match those on the FCT16501T/162501T, allowing an easy upgrade.

CacheRAM CacheRAM CacheRAM Coprocessor C

APPLICATIONS—486 INTERFACE

Figure 1. FCT162701T Application Example

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified: Industrial: TA = -40° C to $+85^{\circ}$ C, VCC = $5.0V \pm 10\%$

Symbol	Parameter	Test Conditi	Test Conditions ⁽¹⁾		Typ. ⁽²⁾	Max.	Unit
Vih	Input HIGH Level	Guaranteed Logic HIGH Level	Guaranteed Logic HIGH Level		—	_	V
VIL	Input LOW Level	Guaranteed Logic LOW Level		_	_	0.8	V
Ін	Input HIGH Current (Input pins) ⁽⁴⁾	Vcc = Max.	VI = VCC	_	_	±1	μA
	Input HIGH Current (I/O pins) ⁽⁴⁾			_	-	±1	
lı.	Input LOW Current (Input pins) ⁽⁴⁾		VI = GND	_	_	±1	
	Input LOW Current (I/O pins) ⁽⁴⁾			_	_	±1	
Іоzн	High Impedance Output Current	Vcc = Max.	Vo = 2.7V	—	—	±1	μA
Iozl	(3-State Output pins) ⁽⁴⁾		Vo = 0.5V	_	_	±1	
Vik	Clamp Diode Voltage	Vcc = Min., IIN = -18mA		-	-0.7	-1.2	V
los	Short Circuit Current	Vcc = Max., Vo = GND ⁽³⁾		-80	-140	-250	mA
Vн	Input Hysteresis	_		—	100	_	mV
ICCL ICCH ICCZ	Quiescent Power Supply Current	Vcc = Max. Vin = GND or Vcc			5	500	μA

OUTPUT DRIVE CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Тур. ⁽²⁾	Max.	Unit
Iodl	Output LOW Current	Vcc = 5V, VIN = VIH or VIL, Vo = $1.5V^{(3)}$		60	115	200	mA
Iodh	Output HIGH Current	$V_{CC} = 5V, V_{IN} = V_{IH} \text{ or } V_{IL}, V_O = 1.5V^{(3)}$		-60	-115	-200	mA
Vон	Output HIGH Voltage	Vcc = Min. Vin = Vih or Vil	Іон = –24mA	2.4	3.3	_	V
Vol	Output LOW Voltage	Vcc = Min. Vin = ViH or ViL	Iol = 24mA	_	0.3	0.55	V

NOTES:

1. For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.

2. Typical values are at Vcc = 5.0V, +25°C ambient.

3. Not more than one output should be shorted at one time. Duration of the test should not exceed one second.

4. The test limit of this parameter is $\pm 5\mu A$ at TA = $-55^{\circ}C$.

POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾			Min.	Тур.(2)	Max.	Unit
Δlcc	Quiescent Power Supply Current TTL Inputs HIGH	$V_{CC} = Max.$ $V_{IN} = 3.4V^{(3)}$			_	0.5	1.5	μA
ICCD (CLK)	Dynamic Power Supply Current due to clock switching ⁽⁴⁾	Vcc = Max. Outputs Open	CLK Toggling 50% Duty Cycling	VIN = VCC VIN = GND	—	180	240	μΑ/ MHz
ICCD (O/P)	Dynamic Power Supply Current due to clock switching ⁽⁴⁾		One Input Toggling 50% Duty Cycle		—	80	120	
IC	Total Power Supply Current ⁽⁶⁾	Vcc = Max. Outputs Open fcP = 10MHz 50% Duty Cycle		Vin = Vcc Vin = GND	_	1.8	2.9 ⁽⁵⁾	mA
	$\overline{OEAB} = GND; \overline{OEBA} = Vcc$ $LE = \overline{WCE} = \overline{RCE} = GND$ $\overline{RESET} = Vcc$ All Inputs Low		VIN = 3.4V VIN = GND	_	2.1	3.7 ⁽⁵⁾		
		Vcc = Max. Outputs Open fcP = 10MHz 50% Duty Cycle		Vin = Vcc Vin = GND	_	2.2	3.5	
		OEAB = GND; OEBLE = WCE = RCE =RESET = Vcc		VIN = 3.4V VIN = GND	_	2.7	5	
		One Bit Toggling at fo = 5MHz 50% Duty Cycle						

NOTES:

- 1. For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.
- 2. Typical values are at Vcc = 5.0V, +25°C ambient.
- 3. Per TTL driven input (VIN = 3.4V). All other inputs at Vcc or GND.
- 4. This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.
- 5. Values for these conditions are examples of the Icc formula. These limits are guaranteed but not tested.
- 6. IC = IQUIESCENT + INPUTS + IDYNAMIC
 - IC = ICC + Δ ICC DHNT + ICCD (CLK) X fCP + ICCD (O/P) X fO NO
 - Icc = Quiescent Current (IccL, IccH and Iccz)
 - Δ Icc = Power Supply Current for a TTL High Input (VIN = 3.4V) DH = Duty Cycle for TTL Inputs High

 - NT = Number of TTL Inputs at D
 - ICCD = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)
 - fcp = Clock Frequency for Register Devices (Zero for Non-Register Devices)
 - fo = Output Frequency
 - No = Number of Outputs at fo

SWITCHING CHARACTERISTICS OVER OPERATING RANGE

				2701T	FCT162701AT		
	Parameter	Test Conditions ⁽¹⁾	Min. ⁽²⁾	Max. ⁽²⁾	Min. ⁽²⁾	Max. ⁽²⁾	Unit
PROPAGAT	ION DELAYS						
1	B1-18 to A1-18	Read path/latch	1.5	6.5	1.5	5.5	ns
2	LE (LOW to HIGH) to A1-18	Read path/latch	1.5	5.7	1.5	4.7	ns
3	CLK to FF	Write path	2	7	2	6	ns
4	CLK to B1-18	Write path	1	6	1	5.2	ns
SETUP & HO	DLD TIMES ⁽³⁾						
5	A1-18 to CLK (LOW to HIGH) Setup	Write path	2.5	-	2.5	_	ns
6	A1-18 to CLK (LOW to HIGH) Hold	Write path	0		0	_	ns
7	B1-18 to LE (HIGH to LOW) Setup	Read path/latch	3	1	3	_	ns
8	B1-18 to LE (HIGH to LOW) Hold	Read path/latch	0	1	0	_	ns
9	WCE, RCE (LOW) to CLK Setup	Write path	3		3	_	ns
10	WCE, RCE (LOW) to CLK Hold	Write path	0		0	_	ns
11	RESET (LOW) to CLK Setup	Write path	3		3	_	ns
12	RESET (LOW) to CLK Hold Write path		0		0	_	ns
ENABLE & D	DISABLE TIMES ⁽³⁾	·	-				
13	OEBA LOW to A1-18 Enable	Write path	1.5	7	1.5	6	ns
14	OEBA HIGH to A1-18 Disable	Write path	1.5	6	1.5	5	ns
15	OEAB LOW to B1-18 Enable	Read path	1.5	7	1.5	6	ns
16	OEAB HIGH to B1-18 Disable	Read path	1.5	6	1.5	5	ns
MINIMUM P	ULSE WIDTHS						
17	CLK HIGH or LOW Pulse Width	Write path	3		3	_	ns
18	LE HIGH Pulse Width	Read path/latch	3	_	3	_	ns

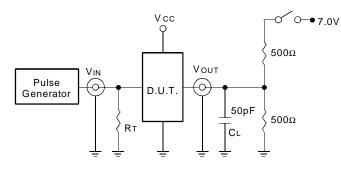
NOTES:

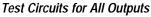
1. See test circuit and waveforms.

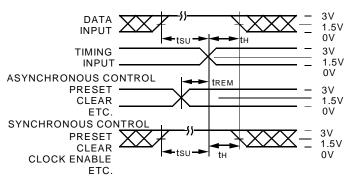
2. Minimum limits are guaranteed but not tested on Propagation Delays.

3. Guaranteed but not tested.

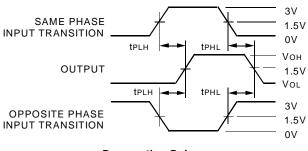
TEST CIRCUITS AND WAVEFORMS







Set-up, Hold, and Release Times



Propagation Delay

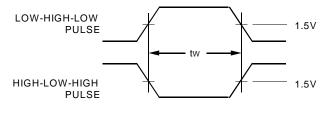
SWITCH POSITION

Test	Switch
Open Drain Disable Low Enable Low	Closed
All Other Tests	Open

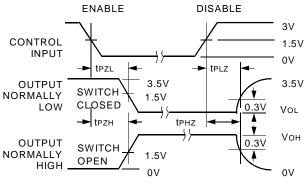
DEFINITIONS:

CL = Load capacitance: includes jig and probe capacitance.

RT = Termination resistance: should be equal to ZOUT of the Pulse Generator.



Pulse Width

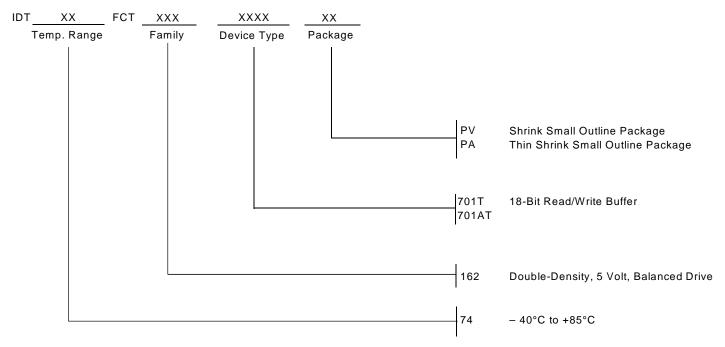


Enable and Disable Times

NOTES:

- 1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.
- 2. Pulse Generator for All Pulses: Rate \leq 1.0MHz; tF \leq 2.5ns; tR \leq 2.5ns.

ORDERING INFORMATION



DATA SHEET DOCUMENT HISTORY

1/21/2002

Removed Military temp grade



CORPORATE HEADQUARTERS 2975 Stender Way Santa Clara, CA 95054 *for SALES:* 800-345-7015 or 408-727-6116 fax: 408-492-8674 www.idt.com for Tech Support: logichelp@idt.com (408) 654-6459